ABSOCIATION CONNECTING ELECTRONICE INDUSTRIES® INCLUSTRIES® INCLUSTRIES®	burn. Illinois. All rights reserved u	nder both This doc level par	rument is a declaraters, the declaration of	ion of the substance encompasses all low	es within the manufactur wer level materials for wl	er listed item. Note: i hich the manufacture	f the item is an as r has engineering	ssembly with lower responsibility.	
IPC Web Site for Information on http://www.ipc.org/IPC-175x	Site for Information on IPC-1752 StandardForm Typeww.ipc.org/IPC-175xDistribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					
Supplier Information									
Company name*	y name* Company unique ID		Unique ID Authority			Response Date*			
onsemi						2025-08-01			
Contact Name	Title - Contact		Phone - Conta	Phone - Contact*			Email - Contact*		
Product-Env-Stewards	Product Enviro Compliance		NA			Product-Env-Stewards@onsemi.com			
Authorized Representative*	sentative* Title - Representative		Phone - Representative*			Email - Representative*			
Product-Env-Stewards Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Iten	n Number Mfr Item Name	Mfr Item Name		Version	Manufacturing Site	Weight*	UOM	Unit Type	
NCV302	25833MTW SPS W/THERMA SHUTDOWN	AL WARNING AND	2025-08-01		PH1	76.555	mg	Each	
Manufacturing Proccess Information									
Terminal Plating / Grid Array Material	Ferminal Base Alloy	J-STD-020 MSL Rating	Peak Proc	ess Body Tempera	ture Max Time at Peak	Temperature Numb	per of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alloy 1		1	260	С	30	seconds 3			
Comments									
evel 1 - maximum time at peak temperature during so	Idering is 10-30 seconds								
For more information regarding material composition	please refer to page 3								

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, admium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part isontains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, is of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not ndependently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the iteratification in this paragraph. If the Company and the Supplier remeties provided as part of hat agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the varranty rights and/or remedies of Supplier's Standard Terms andConditions of									
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).						
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the				
Supplier Digital Signature	astislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	19.1	mg	Supplier	Zinc (Zn)	7440-66-6		0.0229	mg
			Supplier	Iron (Fe)	7439-89-6		0.4489	mg
			Supplier	Copper (Cu)	7440-50-8		18.6225	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0057	mg
Die	2.38	mg	Supplier	Silicon (Si)	7440-21-3		2.38	mg
Die Attach Solder	1.0	mg	Supplier	Silver (Ag)	7440-22-4		0.025	mg
			А	Lead (Pb)	7439-92-1	7a	0.925	mg
			Supplier	Tin (Sn)	7440-31-5		0.05	mg
Ероху	0.75	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0675	mg
			Supplier	Proprietary	Proprietary Data		0.0041	mg
			Supplier	Bismaleimide	13676-54-5		0.3784	mg
			Supplier	PTFE	9002-84-0		0.3	mg
Lead Frame	24.8	mg	Supplier	Iron (Fe)	7439-89-6		0.0248	mg
			Supplier	Copper (Cu)	7440-50-8		24.7752	mg
ead Frame plating	0.4	mg	Supplier	Silver (Ag)	7440-22-4		0.4	mg
Mold Compound-Black	26.0	mg		Epoxy resin	proprietary data		3.458	mg
			Supplier	Carbon Black (C)	1333-86-4		0.052	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		22.49	mg
lating	1.8	mg	Supplier	Tin (Sn)	7440-31-5		1.8	mg
Wire Bond	0.325	825 mg	Supplier	Palladium (Pd)	7440-05-3		0.0068	mg
			Supplier	Gold (Au)	7440-57-5		0.0008	mg
			Supplier	Copper (Cu)	7440-50-8		0.3174	mg